

ABSTRACT OF THE DISCLOSURE

An image sense module includes a semi-conductor image sense chip having a top face attached to a bottom face of a glass plate and multiple electric contacts formed on the semi-conductor image sense chip. A conductive interconnection circuit is formed on the bottom face of the glass plate. The conductive interconnection circuit has multiple first solder points each electrically connected to a corresponding one of the electric contacts of the semi-conductor image sense chip and multiple second solder points formed on one side of the glass plate. A lens set is secured on the glass plate. The lens set includes a holder perpendicularly attached to a top face of the glass plate and having a skirt downward extending from the holder. A channel is defined in one side of the skirt for allowing the conductive interconnection circuit extending through the holder.

15